### DISCRETE SEMICONDUCTORS

# DATA SHEET

## BGY148A; BGY148B UHF amplifier modules

Preliminary specification
File under Discrete Semiconductors, SC09

1996 May 20





## **BGY148A; BGY148B**

#### **FEATURES**

- Single 6 V nominal supply voltage
- 3 W output power
- Easy control of output power by DC voltage
- · Silicon bipolar technology
- Standby current less than 100 μA.

#### **APPLICATIONS**

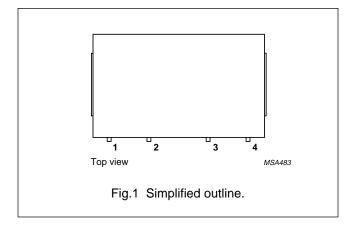
 Portable communication equipment operating in the 400 to 440 MHz and 430 to 488 MHz frequency ranges respectively.

#### **DESCRIPTION**

The BGY148A and BGY148B are three-stage UHF amplifier modules in a SOT421A package. Each module consists of three NPN silicon planar transistor dies mounted together with matching and bias circuit components on a metallized ceramic substrate. The modules produce an output power of 3 W into a load of 50  $\Omega$  with an RF power of 10 mW.

#### **PINNING - SOT421A**

PIN	DESCRIPTION		
1	RF input		
2	V <sub>C</sub>		
3	V <sub>S</sub>		
4	RF output		
Flange	ground		



#### **QUICK REFERENCE DATA**

RF performance at  $T_{mb} = 25$  °C.

TYPE	MODE OF OPERATION	f (MHz)	V <sub>S</sub> (V)	P <sub>L</sub> (W)	G <sub>p</sub> (dB)	η <b>(%)</b>	Z <sub>S</sub> ; Z <sub>L</sub> (Ω)
BGY148A	CW	400 to 440	6	≥3	≥24.8	typ. 53	50
BGY148B	CW	430 to 488	6	≥3	≥24.8	typ. 53	50

BGY148A; BGY148B

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER		MAX.	UNIT
Vs	DC supply voltage	_	8.5	V
V <sub>C</sub>	DC control voltage	_	4	V
P <sub>D</sub>	input drive power		20	mW
$P_{L}$	load power		3.5	W
T <sub>stg</sub>	storage temperature		+100	°C
T <sub>mb</sub>	operating mounting-base temperature		+100	°C

#### **CHARACTERISTICS**

 $Z_S$  =  $Z_L$  = 50  $\Omega;$   $P_D$  = 10 mW;  $V_S$  = 6 V;  $V_C \leq$  3.5 V;  $T_{mb}$  = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f	frequency range					
	BGY148A		400	-	440	MHz
	BGY148B		430	-	488	MHz
IQ	total quiescent current	$V_C = 0; P_D = 0$	_	_	100	μΑ
I <sub>C</sub>	control current	adjust V <sub>C</sub> for P <sub>L</sub> = 3 W	_	_	500	μΑ
$P_{L}$	load power		3	_	_	W
Gp	power gain	adjust V <sub>C</sub> for P <sub>L</sub> = 3 W	24.8	_	_	dB
η	efficiency	adjust V <sub>C</sub> for P <sub>L</sub> = 3 W	46	53	_	%
H <sub>2</sub>	second harmonic	adjust V <sub>C</sub> for P <sub>L</sub> = 3 W	_	_	-38	dBc
H <sub>3</sub>	third harmonic	adjust V <sub>C</sub> for P <sub>L</sub> = 3 W	_	_	-38	dBc
VSWR <sub>in</sub>	input VSWR	adjust V <sub>C</sub> for P <sub>L</sub> = 3 W	_	-	3:1	
	control range	V <sub>C</sub> = 0 to 3.5 V	10	_	_	dB
	stability	$P_D$ = 5 to 20 mW; $V_S$ = 5 to 8.5 V; $P_L \le 3.5$ W; $VSWR \le 4$ : 1 through all phases	_	_	-60	dBc
	ruggedness	$V_S = 8.5 \text{ V}$ ; adjust $V_C$ for $P_L = 3.5 \text{ W}$ ; $VSWR \le 4$ : 1 through all phases	no	degrada	tion	

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## BGY148A; BGY148B

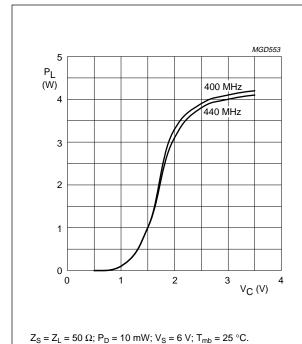


Fig.2 Load power as a function of control voltage; BGY148A; typical values.

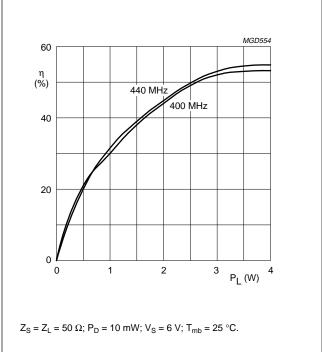


Fig.3 Efficiency as a function of load power; BGY148A; typical values.

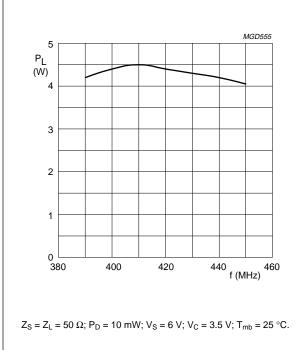
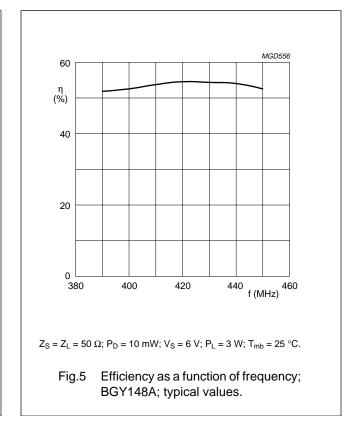


Fig.4 Load power as a function of frequency; BGY148A; typical values.



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## BGY148A; BGY148B

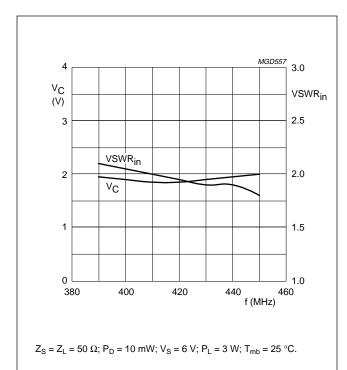


Fig.6 Control voltage and input VSWR as functions of frequency; BGY148A; typical values.

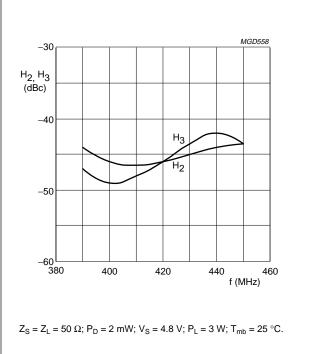
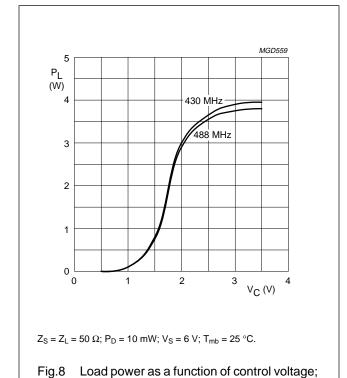
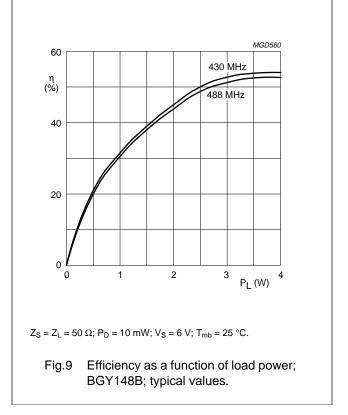


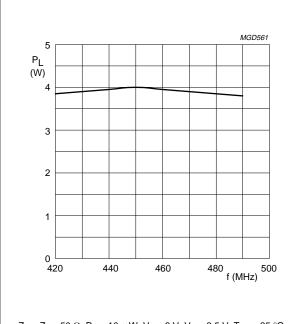
Fig.7 Harmonics as a function of frequency; BGY148A; typical values.



BGY148B; typical values.



## BGY148A; BGY148B



 $Z_S$  =  $Z_L$  = 50  $\Omega;$   $P_D$  = 10 mW;  $V_S$  = 6 V;  $V_C$  = 3.5 V;  $T_{mb}$  = 25 °C.

Fig.10 Load power as a function of frequency; BGY148B; typical values.

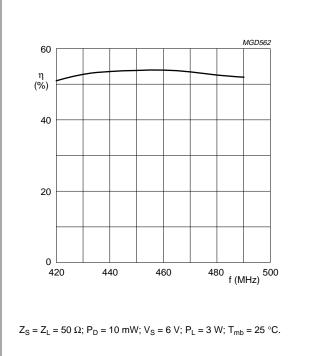


Fig.11 Efficiency as a function of frequency; BGY148B; typical values.

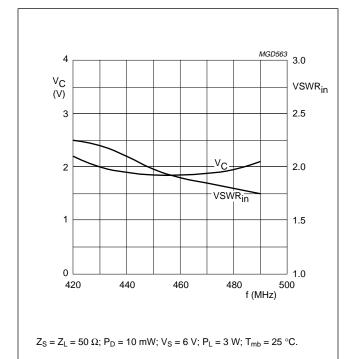
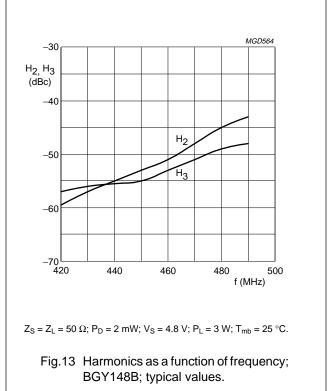


Fig.12 Control voltage and input VSWR as functions of frequency; BGY148B; typical values.



## BGY148A; BGY148B

#### **SOLDERING**

The indicated temperatures are those at the solder interfaces.

Advised solder types are types with a liquidus less than or equal to 210  $^{\circ}\text{C}.$ 

Solder dots or solder prints must be large enough to wet the contact areas.

Footprints for soldering should cover the module contact area +0.1 mm on all sides.

Soldering can be carried out using a conveyor oven, a hot air oven, an infrared oven or a combination of these ovens.

Hand soldering must be avoided because the soldering iron tip can exceed the maximum permitted temperature of  $250~^{\circ}\text{C}$  and damage the module.

The maximum temperature profile and soldering time is indicated as follows (see Fig.14):

t = 350 s at 100 °C

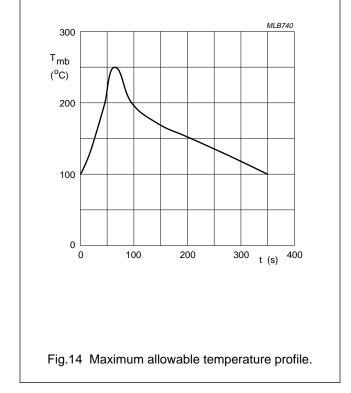
t = 300 s at 125 °C

t = 200 s at 150 °C

t = 100 s at 175 °C

t = 50 s at 200 °C

t = 5 s at 250 °C (maximum temperature).



#### Cleaning

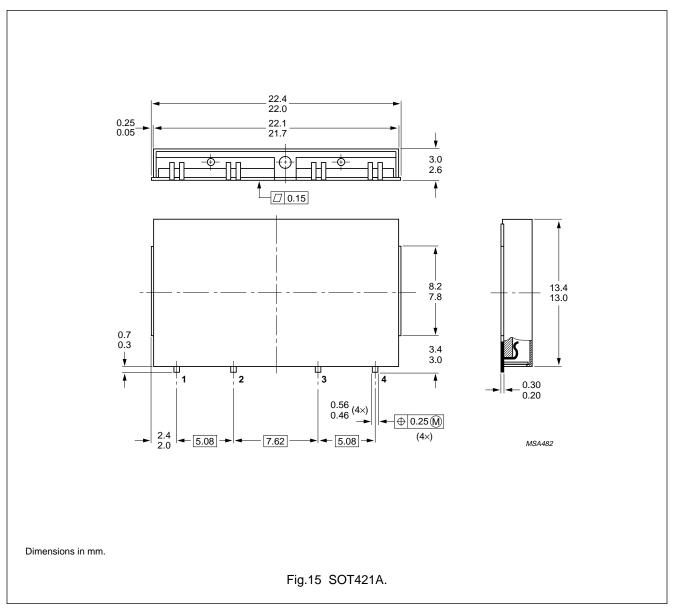
The following fluids may be used for cleaning:

- Alcohol
- Bio-Act (Terpene Hydrocarbon)
- Triclean B/S
- · Acetone.

Ultrasonic cleaning should not be used since this can cause serious damage to the product.

BGY148A; BGY148B

#### **PACKAGE OUTLINE**



BGY148A; BGY148B

#### **DEFINITIONS**

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

#### Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.